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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-VQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at87c52x2-rltum

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

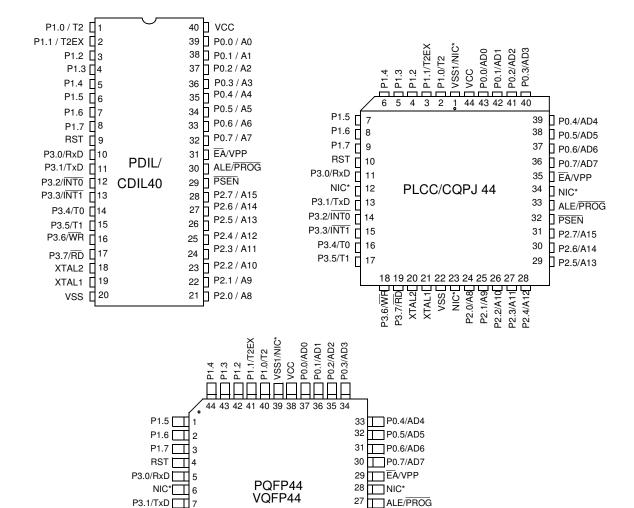
### **SFR Mapping**

The Special Function Registers (SFRs) of the TS80C52X2 fall into the following categories:

- C51 core registers: ACC, B, DPH, DPL, PSW, SP, AUXR1
- I/O port registers: P0, P1, P2, P3
- Timer registers: T2CON, T2MOD, TCON, TH0, TH1, TH2, TMOD, TL0, TL1, TL2, RCAP2L, RCAP2H
- Serial I/O port registers: SADDR, SADEN, SBUF, SCON
- · Power and clock control registers: PCON
- · Interrupt system registers: IE, IP, IPH
- · Others: AUXR, CKCON



### **Pin Configuration**



26 PSEN

25 P2.7/A15

24 P2.6/A14

23 P2.5/A13

\*NIC: No Internal Connection

P3.2/INT0 8 P3.3/INT1 9

P3.4/T0 10

P3.5/T1 11



12 13 14 15 16 17 18 19 20 21 22

XTAL2 XTAL1

VSS

P2.0/A8 P2.1/A9

P2.3/A11

2.2/A10



Mnemonic	I	Pin Nu	mber	Туре	Name and Function
	DIL	LCC	VQFP 1.4		
V <sub>SS</sub>	20	22	16	I	Ground: 0V reference
Vss1		1	39	I	Optional Ground: Contact the Sales Office for ground connection.
V <sub>CC</sub>	40	44	38	I	Power Supply: This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39- 32	43- 36	37-30	I/O	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs.Port 0 pins must be polarized to Vcc
					or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As
					inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification.  Alternate functions for Port 1 include:
	1	2	40	I/O	T2 (P1.0): Timer/Counter 2 external count input/Clockout
	2	3	41	I	T2EX (P1.1): Timer/Counter 2 Reload/Capture/Direction Control
P2.0-P2.7	21- 28	24- 31	18-25	I/O	Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled
					high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX atDPTR). In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX atRi), port 2 emits the contents of the P2 SFR. Some Port 2 pins receive the high order address bits during EPROM programming and verification: P2.0 to P2.4
P3.0-P3.7	10- 17	11, 13- 19	5, 7-13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source
					current because of the internal pull-ups. Port 3 also serves the special features of the 80C51 family, as listed below.
	10	11	5	I	RXD (P3.0): Serial input port
	11	13	7	0	TXD (P3.1): Serial output port
	12	14	8	I	INT0 (P3.2): External interrupt 0

Mnemonic	ı	Pin Nu	mber	Туре	Name and Function	
	DIL	LCC	VQFP 1.4			
	13	15	9	I	INT1 (P3.3): External interrupt 1	
	14	16	10	I	T0 (P3.4): Timer 0 external input	
	15	17	11	I	T1 (P3.5): Timer 1 external input	
	16	18	12	0	WR (P3.6): External data memory write strobe	
	17	19	13	0	RD (P3.7): External data memory read strobe	
Reset	9	10	4	I	<b>Reset:</b> A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V <sub>SS</sub> permits a power-on reset using only an external capacitor to V <sub>CC</sub> .	
ALE/PROG	30	33	27	O (I)	Address Latch Enable/Program Pulse: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input (PROG) during EPROM programming. ALE can be disabled by setting SFR's AUXR.0 bit. With this bit set, ALE will be inactive during internal fetches.	
PSEN	29	32	26	0	Program Store ENable: The read strobe to external program memory. When executing code from the external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.	
EA/V <sub>PP</sub>	31	35	29	I	External Access Enable/Programming Supply Voltage:  EA must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH (RB) or 7FFFH (RC), or FFFFH (RD). If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH (RB) or 7FFFH (RC) EA must be held low for ROMless devices. This pin also receives the 12.75V programming supply voltage (V <sub>PP</sub> ) during EPROM programming. If security level 1 is programmed, EA will be internally latched on Reset.	
XTAL1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.	
XTAL2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier	





### Timer 2

The timer 2 in the TS80C52X2 is compatible with the timer 2 in the 80C52.

It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 5) and T2MOD register (See Table 6). Timer 2 operation is similar to Timer 0 and Timer 1. C/T2 selects  $F_{OSC}/12$  (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and CP/RL2 (T2CON), as described in the Atmel 8-bit Microcontroller Hardware description.

Refer to the Atmel 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C52X2 Timer 2 includes the following enhancements:

- · Auto-reload mode with up or down counter
- Programmable clock-output

#### Auto-reload Mode

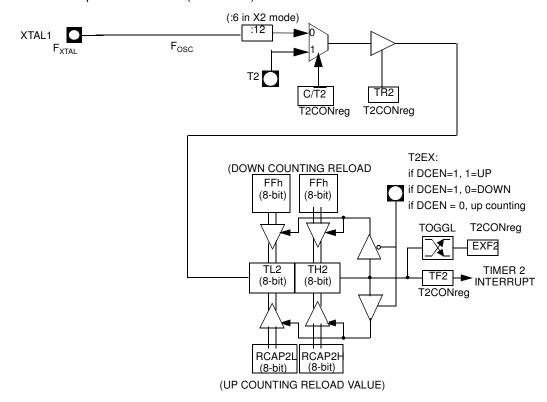
The Auto-reload mode configures timer 2 as a 16-bit timer or event counter with auto-matic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 4. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution.

Figure 4. Auto-reload Mode Up/Down Counter (DCEN = 1)



### **Programmable Clock-output**

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 5) . The input clock increments TL2 at frequency  $F_{OSC}/2$ . The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock - OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz  $(F_{\rm OSC}/2^{16})$  to 4 MHz  $(F_{\rm OSC}/4)$ . The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/T2 bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.



# TS80C52X2 Serial I/O Port

The serial I/O port in the TS80C52X2 is compatible with the serial I/O port in the 80C52. It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

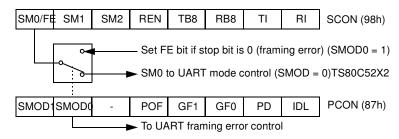
Serial I/O port includes the following enhancements:

- · Framing error detection
- Automatic address recognition

### **Framing Error Detection**

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 6).

Figure 6. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 9.) bit is set.

Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 7. and Figure 8.).

Figure 7. UART Timings in Mode 1

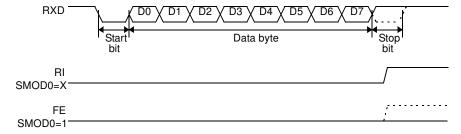
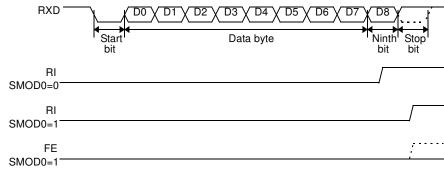






Figure 8. UART Timings in Modes 2 and 3



# Automatic Address Recognition

The automatic address recognition feature is enabled when the multiprocessor communication feature is enabled (SM2 bit in SCON register is set).

Implemented in hardware, automatic address recognition enhances the multiprocessor communication feature by allowing the serial port to examine the address of each incoming command frame. Only when the serial port recognizes its own address, the receiver sets RI bit in SCON register to generate an interrupt. This ensures that the CPU is not interrupted by command frames addressed to other devices.

If desired, you may enable the automatic address recognition feature in mode 1. In this configuration, the stop bit takes the place of the ninth data bit. Bit RI is set only when the received command frame address matches the device's address and is terminated by a valid stop bit.

To support automatic address recognition, a device is identified by a given address and a broadcast address.

Note:

The multiprocessor communication and automatic address recognition features cannot be enabled in mode 0 (i.e. setting SM2 bit in SCON register in mode 0 has no effect).

### **Given Address**

Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed.

To address a device by its individual address, the SADEN mask byte must be 1111 1111b.

### For example:

SADDR0101 0110b SADEN1111 1100b Given0101 01XXb

The following is an example of how to use given addresses to address different slaves:

The SADEN byte is selected so that each slave may be addressed separately. For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g.

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

Note:

If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

Table 15. The State of Ports During Idle and Power-down Modes

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
ldle	Internal	1	1	Port Data <sup>(1)</sup>	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	Internal	0	0	Port Data <sup>(1)</sup>	Port Data	Port Data	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data

Note: 1. Port 0 can force a "zero" level. A "one" will leave port floating.





# ONCE<sup>™</sup> Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C52X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C52X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and PSEN is high.
- Hold ALE low as RST is deactivated.

While the TS80C52X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 16. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull- up	Weak pull- up	Float	Weak pull- up	Weak pull- up	Weak pull- up	Active



### **Reduced EMI Mode**

The ALE signal is used to demultiplex address and data buses on port 0 when used with external program or data memory. Nevertheless, during internal code execution, ALE signal is still generated. In order to reduce EMI, ALE signal can be disabled by setting AO bit.

The AO bit is located in AUXR register at bit location 0. As soon as AO is set, ALE is no longer output but remains active during MOVX and MOVC instructions and external fetches. During ALE disabling, ALE pin is weakly pulled high.

**Table 18.** AUXR Register AUXR - Auxiliary Register (8Eh)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	AO

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
0	AO	ALE Output bit Clear to restore ALE operation during internal fetches. Set to disable ALE operation during internal fetches.

Reset Value = XXXX XXX0b Not bit addressable



### **EPROM Structure**

The TS87C52X2 is divided in two different arrays:

- · the code array: 8 Kbytes
- the encryption array: 64 bytes

In addition a third non programmable array is implemented:

the signature array: 4 bytes

### **EPROM Lock System**

The program Lock system, when programmed, protects the on-chip program against software piracy.

### **Encryption Array**

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

### **Program Lock Bits**

The three lock bits, when programmed according to Table 1., will provide different level of protection for the on-chip code and data.

Program Lock Bits					
Security level	LB1	LB2	LB3	Protection Description	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.	
2	Р	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.	
3	U	Р	U	U Same as 2, also verify is disabled.	
4	U	U	Р	Same as 3, also external execution is disabled.	

U: unprogrammed P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

### **Signature Bytes**

The TS80/87C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

### **EPROM Programming**

### Set-up modes

In order to program and verify the EPROM or to read the signature bytes, the TS87C52X2 is placed in specific set-up modes (See Figure 11.).

 $12,000~\mu\text{W/cm}^2$  rating for 30 minutes, at a distance of about 25 mm, should be sufficient. An exposure of 1 hour is recommended with most of standard erasers.

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelength shorter than approximately 4,000 Å. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the device to this type of exposure, it is suggested that an opaque label be placed over the window.

### **Signature Bytes**

The TS80/87C52X2 has four signature bytes in location 30h, 31h, 60h and 61h. To read these bytes follow the procedure for EPROM verify but activate the control lines provided in Table 31. for Read Signature Bytes. Table 35. shows the content of the signature byte for the TS80/87C52X2.

**Table 21.** Signature Bytes Content

Location	Contents	Comment	
30h	58h	Manufacturer Code: Atmel	
31h	57h	Family Code: C51 X2	
60h	2Dh	Product name: TS80C52X2	
60h	ADh	Product name:TS87C52X2	
60h	20h	Product name: TS80C32X2	
61h	FFh	Product revision number	



Port 0: 26 mA

Ports 1, 2 and 3: 15 mA

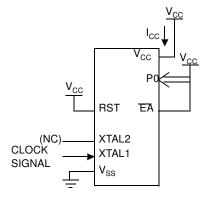
Maximum total  $I_{OL}$  for all output pins: 71 mA

If  $I_{OL}$  exceeds the test condition,  $V_{OL}$  may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

- 7. For other values, please contact your sales office.
- 8. Operating  $I_{CC}$  is measured with all output pins disconnected; XTAL1 driven with  $T_{CLCH}$ ,  $T_{CHCL} = 5$  ns (see Figure 17.),  $V_{IL} = V_{SS} + 0.5V$ ,

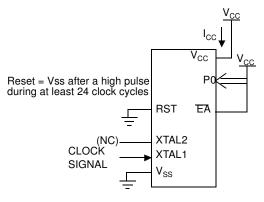
 $V_{IH} = V_{CC} - 0.5V$ ; XTAL2 N.C.;  $\overline{EA} = Port \ 0 = V_{CC}$ ; RST =  $V_{SS}$ . The internal ROM runs the code 80 FE (label: SJMP label).  $I_{CC}$  would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.

Figure 13. I<sub>CC</sub> Test Condition, under reset



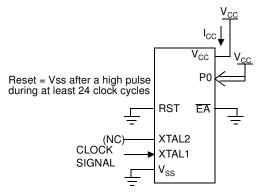
All other pins are disconnected.

Figure 14. Operating I<sub>CC</sub> Test Condition



All other pins are disconnected.

Figure 15. I<sub>CC</sub> Test Condition, Idle Mode



All other pins are disconnected.



Table 28., Table 31. and Table 34. give the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-M, -V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 25. Max frequency for derating formula regarding the speed grade

	-M X1 mode	-M X2 mode	-V X1 mode	-V X2 mode	-L X1 mode	-L X2 mode
Freq (MHz)	40	20	40	30	30	20
T (ns)	25	50	25	33.3	33.3	50

### Example:

 $T_{LLIV}$  in X2 mode for a -V part at 20 MHz (T =  $1/20^{E6}$  = 50 ns):

$$T_{LLIV} = 2T - x = 2 \times 50 - 22 = 78$$
ns

### **External Program Memory** Characteristics

Table 26. Symbol Description

Symbol	Parameter
Т	Oscillator clock period
T <sub>LHLL</sub>	ALE pulse width
T <sub>AVLL</sub>	Address Valid to ALE
T <sub>LLAX</sub>	Address Hold After ALE
T <sub>LLIV</sub>	ALE to Valid Instruction In
T <sub>LLPL</sub>	ALE to PSEN
T <sub>PLPH</sub>	PSEN Pulse Width
T <sub>PLIV</sub>	PSEN to Valid Instruction In
T <sub>PXIX</sub>	Input Instruction Hold After PSEN
T <sub>PXIZ</sub>	Input Instruction FloatAfter PSEN
T <sub>PXAV</sub>	PSEN to Address Valid
T <sub>AVIV</sub>	Address to Valid Instruction In
T <sub>PLAZ</sub>	PSEN Low to Address Float

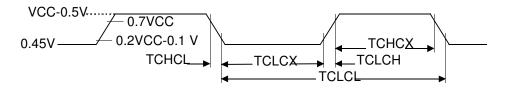
# External Clock Drive Characteristics (XTAL1)

Table 36. AC Parameters

Symbol	Parameter	Min	Max	Units
T <sub>CLCL</sub>	Oscillator Period	25		ns
T <sub>CHCX</sub>	High Time	5		ns
T <sub>CLCX</sub>	Low Time	5		ns
T <sub>CLCH</sub>	Rise Time		5	ns
T <sub>CHCL</sub>	Fall Time		5	ns
T <sub>CHCX</sub> /T <sub>CLCX</sub>	Cyclic ratio in X2 mode	40	60	%

### **External Clock Drive Waveforms**

Figure 23. External Clock Drive Waveforms



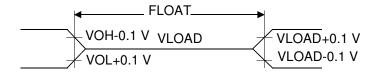
### AC Testing Input/Output Waveforms

Figure 24. AC Testing Input/Output Waveforms

AC inputs during testing are driven at  $V_{CC}$  - 0.5 for a logic "1" and 0.45V for a logic "0". Timing measurement are made at  $V_{IH}$  min for a logic "1" and  $V_{IL}$  max for a logic "0".

#### **Float Waveforms**

Figure 25. Float Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded  $V_{OH}/V_{OL}$  level occurs.  $I_{OL}/I_{OH} \ge \pm 20$ mA.



### **Ordering Information**

Table 37. Possible Ordering Entries

Part Number <sup>(3)</sup>	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing		
TS80C32X2-MCA								
TS80C32X2-MCB								
TS80C32X2-MCC								
TS80C32X2-MCE								
TS80C32X2-LCA								
TS80C32X2-LCB								
TS80C32X2-LCC								
TS80C32X2-LCE								
TS80C32X2-VCA								
TS80C32X2-VCB								
TS80C32X2-VCC	OBSOLETE							
TS80C32X2-VCE								
TS80C32X2-MIA								
TS80C32X2-MIB								
TS80C32X2-MIC								
TS80C32X2-MIE								
TS80C32X2-LIA								
TS80C32X2-LIB								
TS80C32X2-LIC								
TS80C32X2-LIE								
TS80C32X2-VIA								
TS80C32X2-VIB								
TS80C32X2-VIC								
TS80C32X2-VIE								
<b>AT80C32X2</b> -3CSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	PDIL40	Stick		
AT80C32X2-SLSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	PLCC44	Stick		
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	VQFP44	Tray		
AT80C32X2-RLRUM	ROMLess	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	VQFP44	Tape & Reel		
AT80C32X2-SLRUM	ROMLess	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	PLCC44	Tape & Reel		
AT80C32X2-3CSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz <sup>(1)</sup>	PDIL40	Stick		





 Table 37. Possible Ordering Entries (Continued)

Part Number <sup>(3)</sup>	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing		
AT80C32X2-SLSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz <sup>(1)</sup>	PLCC44	Stick		
AT80C32X2-RLTUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz <sup>(1)</sup>	VQFP44	Tray		
AT80C32X2-3CSUV	ROMLess	5V ±10%	Industrial & Green	60 MHz <sup>(3)</sup>	PDIL40	Stick		
AT80C32X2-SLSUV	ROMLess	5V ±10%	Industrial & Green	60 MHz <sup>(3)</sup>	PLCC44	Stick		
AT80C32X2-RLTUV	ROMLess	5V ±10%	Industrial & Green	60 MHz <sup>(3)</sup>	VQFP44	Tray		
TS80C52X2zzz-MCA								
TS80C52X2zzz-MCB								
TS80C52X2zzz-MCC								
TS80C52X2zzz-MCE								
TS80C52X2zzz-LCA								
TS80C52X2zzz-LCB								
TS80C52X2zzz-LCC								
TS80C52X2zzz-LCE								
TS80C52X2zzz-VCA	OBSOLETE							
TS80C52X2zzz-VCB								
TS80C52X2zzz-VCC								
TS80C52X2zzz-VCE								
TS80C52X2zzz-MIA								
TS80C52X2zzz-MIB								
TS80C52X2zzz-MIC								
TS80C52X2zzz-MIE								
TS80C52X2zzz-LIA								
TS80C52X2zzz-LIB								
TS80C52X2zzz-LIC								
TS80C52X2zzz-LIE								
TS80C52X2zzz-VIA								
TS80C52X2zzz-VIB								
TS80C52X2zzz-VIC								
TS80C52X2zzz-VIE								
AT80C52X2zzz-3CSUM	8K ROM	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	PDIL40	Stick		
AT80C52X2zzz-SLSUM	8K ROM	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	PLCC44	Stick		



Table 37. Possible Ordering Entries (Continued)

Part Number <sup>(3)</sup>	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT87C52X2-SLSUM	8K OTP	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	PLCC44	Stick
AT87C52X2-RLTUM	8K OTP	5V ±10%	Industrial & Green	40 MHz <sup>(1)</sup>	VQFP44	Tray
AT87C52X2-3CSUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz <sup>(1)</sup>	PDIL40	Stick
AT87C52X2-SLSUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz <sup>(1)</sup>	PLCC44	Stick
AT87C52X2-RLTUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz <sup>(1)</sup>	VQFP44	Tray
AT87C52X2-3CSUV	8K OTP	5V ±10%	Industrial & Green	60 MHz <sup>(3)</sup>	PDIL40	Stick
AT87C52X2-SLSUV	8K OTP	5V ±10%	Industrial & Green	60 MHz <sup>(3)</sup>	PLCC44	Stick
AT87C52X2-RLTUV	8K OTP	5V ±10%	Industrial & Green	60 MHz <sup>(3)</sup>	VQFP44	Tray

Notes:

- 1. 20 MHz in X2 Mode.
- 2. Tape and Reel available for SL, PQFP and RL packages
- 3. 30 MHz in X2 Mode.



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